

## FQB12P20-VB Datasheet

### P-Channel 200 V (D-S) MOSFET

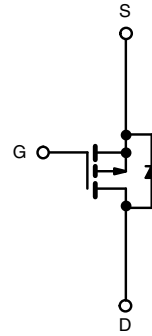
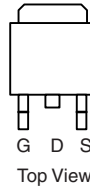
PRODUCT SUMMARY		
$V_{DS}$ (V)	-200	
$R_{DS(on)}$ ( $\Omega$ )	$V_{GS} = -10$ V	0.50
$Q_g$ max. (nC)	44	
$Q_{gs}$ (nC)	7.1	
$Q_{gd}$ (nC)	27	
Configuration	Single	

#### FEATURES

- Dynamic  $dV/dt$  rating
- Repetitive avalanche rated
- P-channel
- Fast switching
- Ease of paralleling
- Simple drive requirements



TO-263



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V <sub>DS</sub>	-200	V	
Gate-Source Voltage			V <sub>GS</sub>	± 20	V	
Continuous Drain Current	V <sub>GS</sub> at -10 V	T <sub>C</sub> = 25 °C	I <sub>D</sub>	-11	A	
		T <sub>C</sub> = 100 °C		-6.8		
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	-44		
Linear Derating Factor				1.0	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	700	mJ	
Repetitive Avalanche Current <sup>a</sup>			I <sub>AR</sub>	-11	A	
Repetitive Avalanche Energy <sup>a</sup>			E <sub>AR</sub>	13	mJ	
Maximum Power Dissipation		T <sub>C</sub> = 25 °C		P <sub>D</sub>	125	W
Peak Diode Recovery dV/dt <sup>c</sup>			dV/dt	-5.0	V/ns	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Soldering Recommendations (Peak temperature) <sup>d</sup>		for 10 s		300		
Mounting Torque	6-32 or M3 screw			10	lbf · in	
				1.1	N · m	



#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).  
 b.  $V_{DD} = -50$  V, starting  $T_J = 25\text{ }^{\circ}\text{C}$ ,  $L = 8.7$  mH,  $R_g = 25\text{ }\Omega$ ,  $I_{AS} = -11$  A (see fig. 12).  
 c.  $I_{SD} \leq -11$  A,  $dI/dt \leq 150$  A/ $\mu\text{s}$ ,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 150\text{ }^{\circ}\text{C}$ .  
 d. 1.6 mm from case.

**THERMAL RESISTANCE RATINGS**

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{thJA}$	-	62	°C/W
Case-to-Sink, Flat, Greased Surface	$R_{thCS}$	0.50	-	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	1.0	

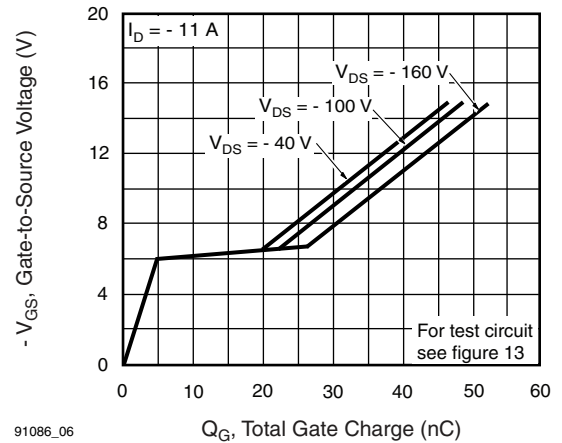
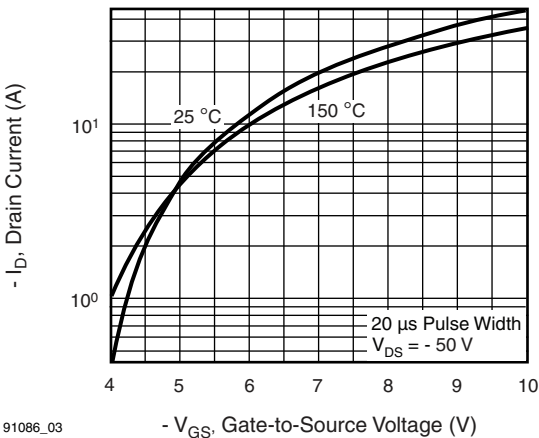
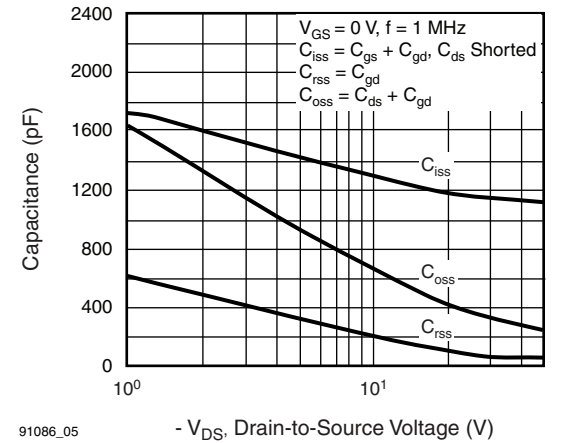
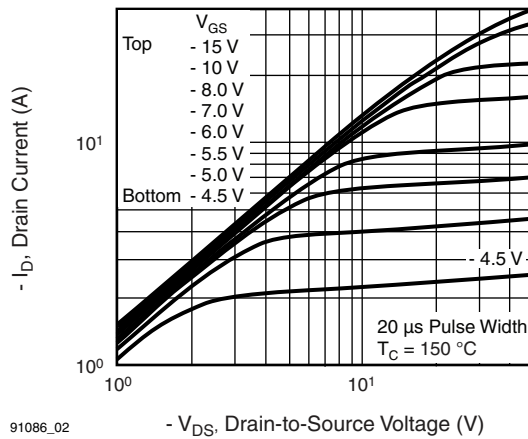
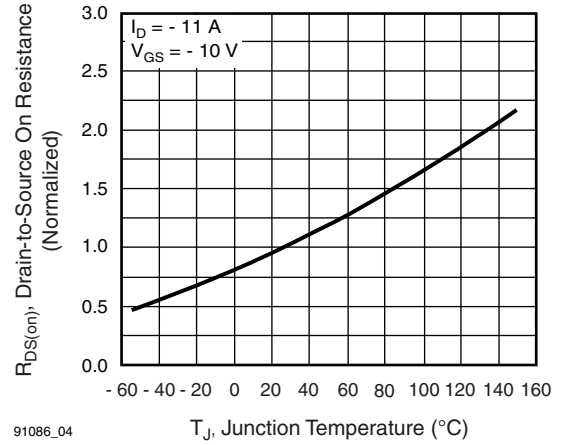
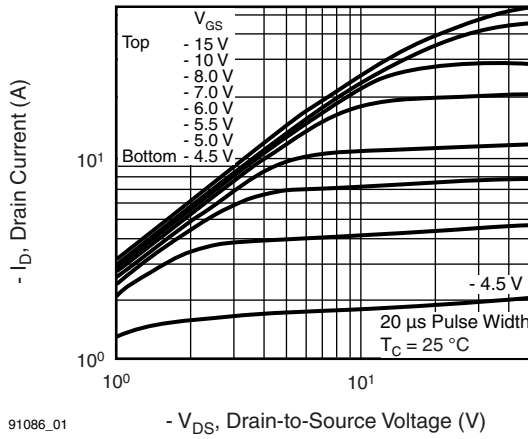
**SPECIFICATIONS** ( $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted)

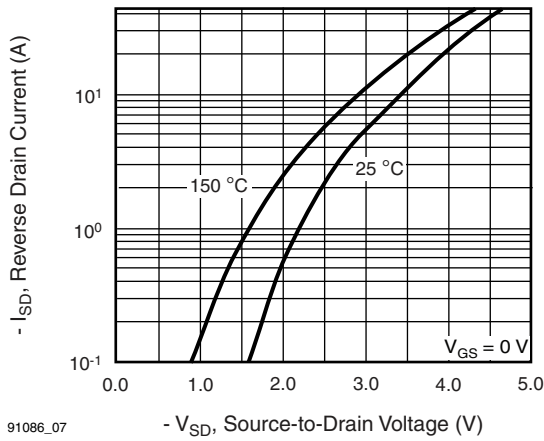
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}$ , $I_D = -250\text{ }\mu\text{A}$	-200	-	-	V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^{\circ}\text{C}$ , $I_D = -1\text{ mA}$	-	-0.2	-	V/ $^{\circ}\text{C}$
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = -250\text{ }\mu\text{A}$	-2.0	-	-4.0	V
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20\text{ V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -200\text{ V}$ , $V_{GS} = 0\text{ V}$	-	-	-100	$\mu\text{A}$
		$V_{DS} = -160\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 125\text{ }^{\circ}\text{C}$	-	-	-500	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = -10\text{ V}$ , $I_D = -6.6\text{ A}^b$	-	0.50	-	$\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS} = -50\text{ V}$ , $I_D = -6.6\text{ A}^b$	4.1	-	-	S
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}$ , $V_{DS} = -25\text{ V}$ , $f = 1.0\text{ MHz}$ , see fig. 5	-	1200	-	pF
Output Capacitance	$C_{oss}$		-	370	-	
Reverse Transfer Capacitance	$C_{rss}$		-	81	-	
Total Gate Charge	$Q_g$	$V_{GS} = -10\text{ V}$ , $I_D = -11\text{ A}$ , $V_{DS} = -160\text{ V}$ , see fig. 6 and 13 <sup>b</sup>	-	-	44	nC
Gate-Source Charge	$Q_{gs}$		-	-	7.1	
Gate-Drain Charge	$Q_{gd}$		-	-	27	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -100\text{ V}$ , $I_D = -11\text{ A}$ $R_g = 9.1\text{ }\Omega$ , $R_D = 8.6\text{ }\Omega$ , see fig. 10 <sup>b</sup>	-	14	-	ns
Rise Time	$t_r$		-	43	-	
Turn-Off Delay Time	$t_{d(off)}$		-	39	-	
Fall Time	$t_f$		-	38	-	
Internal Drain Inductance	$L_D$	Between lead, 6 mm (0.25") from package and center of die contact 	-	4.5	-	nH
Internal Source Inductance	$L_S$		-	7.5	-	
Gate Input Resistance	$R_g$	$f = 1\text{ MHz}$ , open drain	0.3	-	1.7	$\Omega$
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p-n junction diode 	-	-	-11	A
Pulsed Diode Forward Current <sup>a</sup>	$I_{SM}$		-	-	-44	
Body Diode Voltage	$V_{SD}$	$T_J = 25\text{ }^{\circ}\text{C}$ , $I_S = -11\text{ A}$ , $V_{GS} = 0\text{ V}^b$	-	-	-5	V
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J = 25\text{ }^{\circ}\text{C}$ , $I_F = -11\text{ A}$ , $dI/dt = 100\text{ A}/\mu\text{s}^b$	-	250	300	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	2.9	3.6	$\mu\text{C}$
Forward Turn-On Time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )				

**Notes**

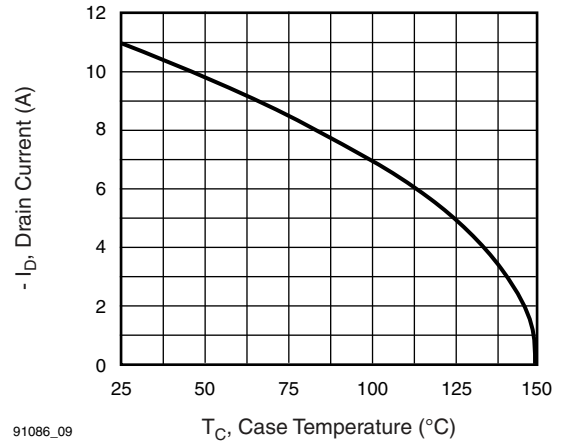
- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).  
 b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

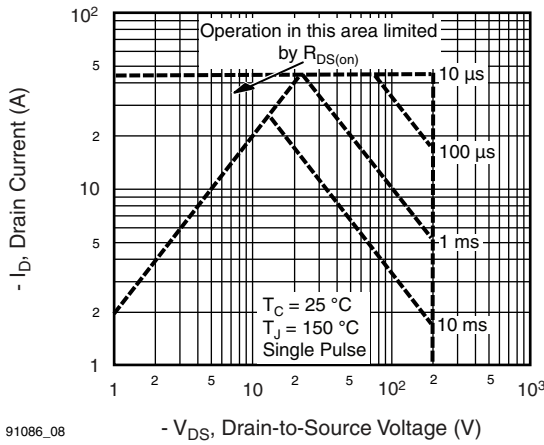




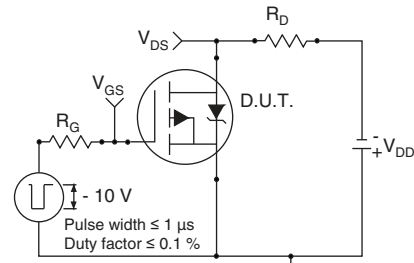
**Fig. 7 - Typical Source-Drain Diode Forward Voltage**



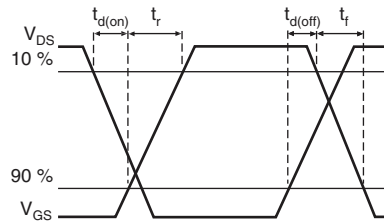
**Fig. 9 - Maximum Drain Current vs. Case Temperature**



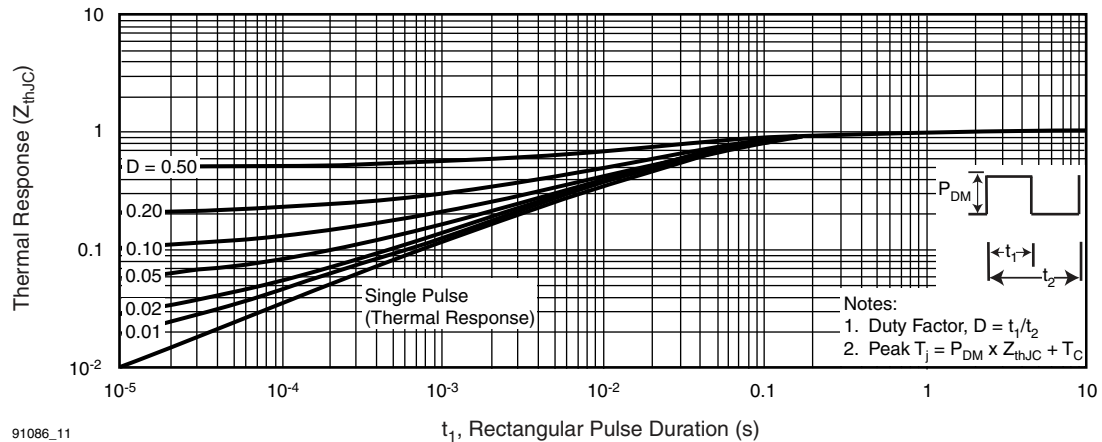
**Fig. 8 - Maximum Safe Operating Area**



**Fig. 10a - Switching Time Test Circuit**



**Fig. 10b - Switching Time Waveforms**



**Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**

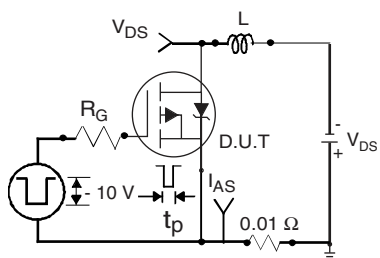


Fig. 12a - Unclamped Inductive Test Circuit

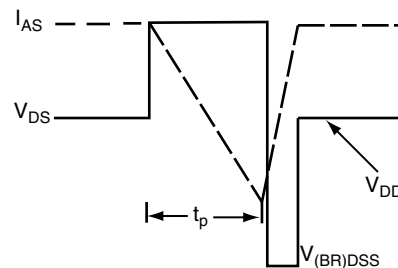


Fig. 12b - Unclamped Inductive Waveforms

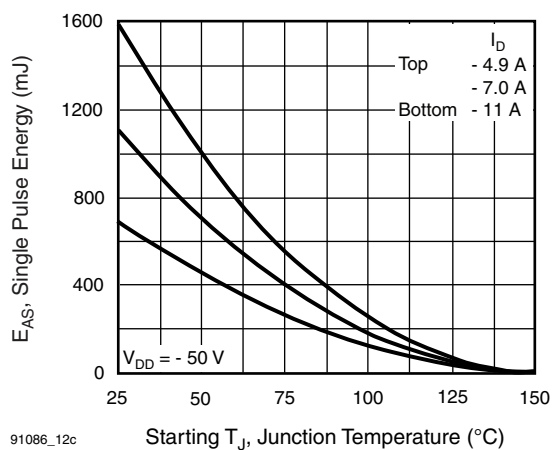


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

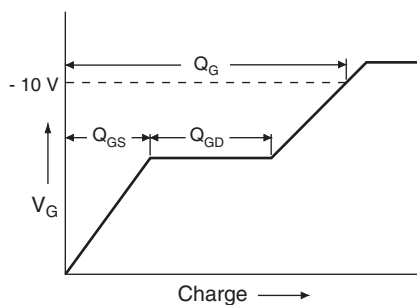


Fig. 13a - Basic Gate Charge Waveform

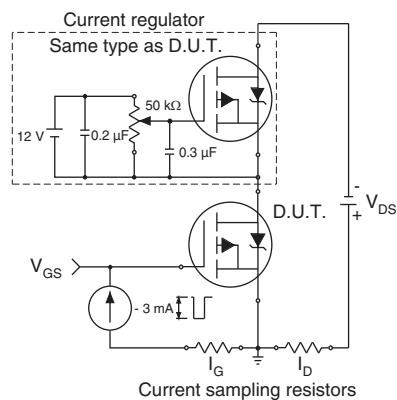
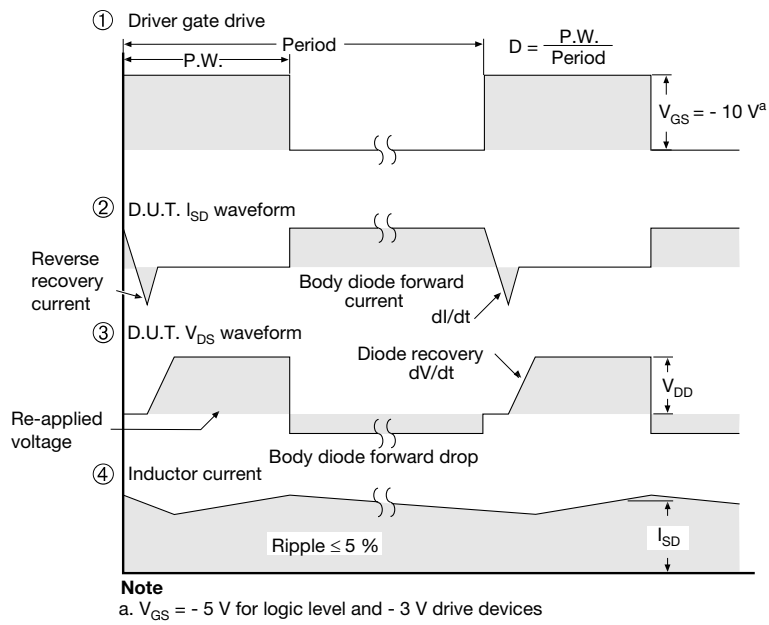
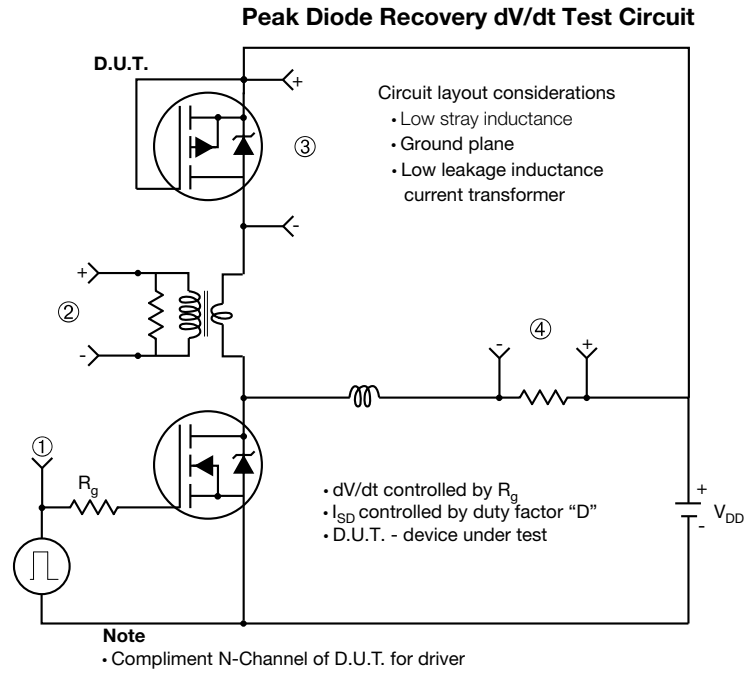
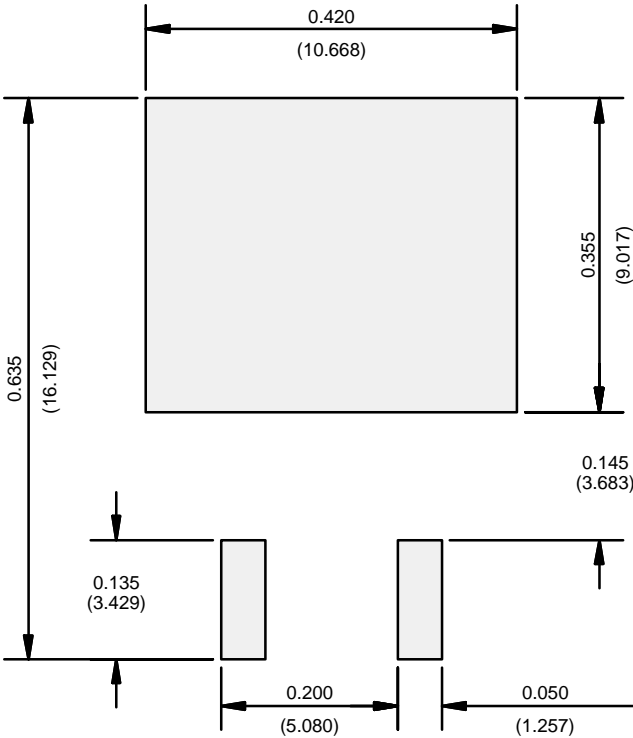


Fig. 13b - Gate Charge Test Circuit



**Fig. 14 - For P-Channel**

RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead



Recommended Minimum Pads  
Dimensions in Inches/(mm)

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